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**AMENDMENT UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE -  
EXAMINING GROUP 2827**

Box AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

**PATENT**  
Attorney Docket No.: 16869P-010700US  
Client Ref. No.: 349905249US1

On 7/25/03

TOWNSEND and TOWNSEND and CREW LLP

By: 

OK TO ENTER: /J.m.m/

04/03/2008

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:

Kouichi Takahashi, et al.

Application No.: 09/590,897

Filed: June 9, 2000

For: SEALING STRUCTURE FOR  
MULTI-CHIP MODULE

Examiner: James M. Mitchell

**AMENDMENT UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE EXAMINING  
GROUP 2827**

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OCT 16 2003

**OFFICIAL**

Box AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Final Office Action mailed March 25, 2003, please  
amend this application as follows: